Basic Packaging Workshop (BPW)

Thursday 4 December 2008

Hosted by: UNISEM, South Wales -NP11 3XT

Device packaging is now the cornerstone of the industry and is a key skill now needed by managers, engineers and technicians in the electronics chip design, development and manufacturing market as well as University academics and Institute professionals.

An Opportunity to gain knowledge and understanding about the basic technology holding Electronic systems together. A day workshop will cover the 4 main topics of :

- **Package trends and technologies** including a Market briefing and an insight into Package technology trends and developments.
- **Mounting Die** including work on Die prep and Epoxy / Eutectic materials and processes.
- **Die Interconnection**, covering the Ins & outs of wirebonding, Flip chip and die stacking.
- **Test verification & Reliability** looking at pull/Shear test equipment and general Package testing.

There will also be the opportunity to see High Tech Packaging in action with a Factory - Window Tour of the UNISEM facility.

Prices: Students £15.00 + vat, IMAPS-UK & NMI members £25.00 + vat, Others £35 + vat

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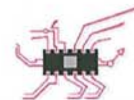

Welsh Electronics Forum

International Microelectronics And Packaging Society

"Everything in electronics between the chip and the system ..."

To be updated on this and future IMAPS-UK events please e-mail your contact details to imapsuk@aol.com

Basic Packaging Workshop
AGENDA

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9.00 am – Registration

9.30 – 10.30 Session 1 - Package trends and technologies

a) Market briefing – Andy Longford, **PandA Europe**

b) Package technology trends and developments. - **UNISEM**

11.00 – 12.00 Session 2 - Mounting Die

a) Die prep – John Sweet, **LOADPOINT**

b) Epoxy / Eutectic materials and processes. – Mark Currie, **HENKEL**

12.00 – 12.30 Factory Tour

Lunch break

1.30 – 2.30 Session 3 - Die Interconnection

a) Ins & outs of wirebonding – Hugh de Lacy, **TS2 Micro**

b) Flip chip and die stacking. – **TWI**

3.00 – 4.00 Session 4 - Test verification & Reliability

a) pull/Shear test equipment - Dr Stephen Clark, **DAGE**

b) Package testing. – Iain Gardiner, **WAFERDATA**

Close

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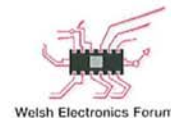

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Booking Form
Basic Packaging Workshop (BPW)
Thursday 4 December 2008

Please Reserve me the following places on the IMAPS-UK Basic Packaging Workshop to be held at UNISEM South Wales on Thursday 4th December 2008

IMAPS-UK or NMI member/s at £25.00 + vat Number of places ____

Students at £15.00 + vat Number of places ____

Non Members at £35 + vat Number of places ____

Names of Attendees:

Contact Details:
Name

Address

Phone Fax e-mail

Payment Method:

Cheque Enclosed (make payable to IMAPS-UK) ☐

Credit/ Debit Card (Visa/Master Card/Maestro/Amex) ☐

Card Holders Name:

Card Number Expiry Date Issue No (Maestro only)

Please return the form to:
IMAPS-UK Secretariat, 4 The Close, Bracebridge Heath, Lincoln, LN4 2PB, UK
Fax +44 (0)1522 575582 e-mail imapsuk@aol.com